

Title (en)
COPPER FOIL COMPOSITE

Title (de)
KUPFERFOLIENVERBUNDSTOFF

Title (fr)
COMPOSITE DE FEUILLE DE CUIVRE

Publication
EP 2439063 A4 20130501 (EN)

Application
EP 10796975 A 20100603

Priority
• JP 2010059416 W 20100603
• JP 2009161068 A 20090707

Abstract (en)
[origin: EP2439063A1] A copper foil composite comprising a copper foil and a resin layer laminated thereon, wherein elongation after fracture of the copper foil is 5% or more, and wherein $(F \times T)/(f \times t) \geq 1$ is satisfied when t is a thickness of the copper foil, f is a stress of the copper foil under tensile strain of 4%, T is a thickness of the resin layer and F is a stress of the resin layer under tensile strain of 4%.

IPC 8 full level
B32B 15/08 (2006.01); **B32B 7/02** (2006.01); **B32B 15/20** (2006.01); **H05K 1/09** (2006.01); **H05K 9/00** (2006.01)

CPC (source: EP KR US)
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Citation (search report)
• [A] US 6217996 B1 20010417 - YAMAMOTO TOMOHIKO [JP], et al
• [A] US 6251507 B1 20010626 - YAMAMOTO TOMOHIKO [JP], et al
• [A] JP 2009108376 A 20090521 - NIKKO KINZOKU KK
• [A] JP 2008120081 A 20080529 - JOINSET CO LTD
• See references of WO 2011004664A1

Cited by
EP3376841A1; US10609849B2

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK SM TR

DOCDB simple family (publication)
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